2<sup>nd</sup> Call for Papers

The International Conference on Leading Edge Manufacturing/Materials&Processing (LEM&P 2020)

June. 22 (Mon) to 26 (Fri), 2020 Duke Energy Convention Center Cincinnati, OH, USA

Organized by: Manufacturing and Machine Tool Division, JSME Co-organized by: Materials and Processing Division, JSME Manufacturing System Division, JSME

## Co-located in MSEC/NAMRC/LEM&P 2020

**Co-sponsors:** 

American Society of Mechanical Engineers (ASME)
Society of Manufacturing Engineers (SME)
The Japan Society of Mechanical Engineers (JSME)











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# The International Conference on Leading Edge Manufacturing/Materials & Processing (LEM&P 2020) June 22 (Mon.) to 26 (Fri.), 2020, Cincinnati, OH, USA

The International Conference on Leading Edge Manufacturing/Materials & Processing (LEM&P) is held at Duke Energy Convention Center in Cincinnati, OH, USA, co-located in MSEC(Manufacturing Science Engineering Conference)/ASME and NAMRC (North American Manufacturing Research Conference)/SME. LEM&P aims to provide an atmosphere for researchers and engineers to discuss, exchange and expose ideas, methods and results in conventional, contemporary and future topics related to a wide variety of manufacturing technologies.

LEM&P calls papers for oral and poster sessions. The papers for oral sessions will be presented in 30 min including discussions; and the posters will be presented in 90 min sessions with short presentations.

#### Organized sessions:

Track 1: Machine tool technologies

1-1 Advanced machine tools

1-2 Evaluation of machine tool performance

1-3 Mechatronics and control technologies

1-4 Machine and mechanical elements

Track 2: Machining processes

2-1 Cutting technologies

2-2 Grinding technologies

2-3 Finishing technologies

Track 3: Non-traditional processes

3-1 Electrical machining

3-2 Energy beam processing

Track 4: Micro manufacturing and surface technology

4-1 Nano/Micro machining

4-2 Micro-manufacturing for science

4-3 Surface machining/treatments and tribology

Track 5: Metrogy, monitoring and evaluation

5-1 Nano/Micro measurement and intelligent instruments

5-2 Monitoring of machining process

5-3 Dynamic behavior of materials and structures

5-4 Nondestructive Evaluations for materials, structures

and processing

Track 6: Additive manufacturing

6-1 Rapid prototyping technologies

6-2 Micro-structure of the metal/materials fabricated by additive manufacturing

Track 7: Manufacturing systems

7-1 Digital design and digital manufacturing (CAD / CAM)

7-2 Manufacturing systems and scheduling

Track 8: Materials

8-1 Advanced materials and applications (metal, polymer, ceramics, composites, smart materials and porous materials)

8-2 Advanced structural/functional materials

Track 9: Material processing

9-1 Advances Material Processing

9-2 Powder Metallurgy Materials and Processing

9-3 Advanced Casting and Semisolid Forming Techniques

9-4 Advanced Welding and Joining Technologies

9-5 Advances in Molding Processing

#### Important dates

Deadline of paper application with abstract: October 18, 2019 (The deadline is not extended any more.)

Notification of tentative acceptance based on abstract: October 21, 2019

Deadline of camera-ready manuscript submission: November 18, 2019

Notification of paper acceptance: February 3, 2020

Deadline of final camera-ready manuscript: March 23, 2020

#### Abstract submission

An abstract of about 200 words is required for every paper. Please fill up the paper title, the authors' information and abstract in the website (https://lemp.secure-platform.com/a/organizations/main/home). The submission deadline is: October 18, 2019.

#### Paper submission

All manuscripts should be prepared on conference paper template. The manuscript should be between 2 and 6 pages in length, and submitted in a PDF file on the conference website. The submission deadline is: November 18, 2019.

#### Conference Organization

Takayuki Goto, Mitsubishi Heavy Industry Machine Tool Co., Ltd.

Atsushi Matsubara, Professor, Kyoto University
Keiichi Shirase, Professor, Kobe University
Seiich Hata, Professor, Nagoya University

Takashi Matsumura, Professor, Tokyo Denki University

Satoshi Kishimoto, National Institute for Material Science

Yasuhiro Takaya, Professor, Osaka University Soichi Ibaraki, Professor, Hiroshima University Norikazu Suzuki, Assoc. Prof., Nogoya University

#### Venue

Venue for technical sessions: Duke Energy Convention Center, OH (http://www.duke-energycenter.com/)

 $Conference\ hotel\ for\ events:\ Hilton\ Cincinnati\ Netherland\ Plaza (\ https://www3.hilton.com/en/hotels/ohio/hilton-cincinnati-netherland-plaza-CVGNPHF/index.html) (\ https://www3.hilton-cincinnati-netherland-plaza-CVGNPHF/index.html) (\ https://www3.hilton-cincinnati-netherland-plaza-CVGNPHF/index.html) (\ https://www3.hilton-cincinnati-netherland-plaza-CVGNPHF/index.html) (\ https://www$ 

General contact(Tentative)

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Conference webpage <a href="https://event.asme.org/LEMP">https://event.asme.org/LEMP</a>